TK13A45D



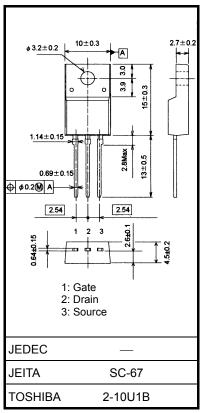
Switching Regulator Applications

Unit: mm

- Low drain-source ON-resistance: $R_{DS (ON)} = 0.38 \Omega (typ.)$
- High forward transfer admittance: $|Y_{fS}| = 6.0 \text{ S (typ.)}$
- Low leakage current: $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 450 \text{ V)}$
- Enhancement mode: V_{th} = 2.0 to 4.0 V (V_{DS} = 10 V, I_D = 1 mA)

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	450	V
Gate-source voltage		V _{GSS}	±30	V
Drain current	DC (Note 1)	I _D	13	
	Pulse (t = 1 ms) (Note 1)	I _{DP}	52	Α
Drain power dissipation (Tc = 25°C)		PD	45	W
Single pulse avalanche energy (Note 2)		E _{AS}	372	mJ
Avalanche current		I _{AR}	13	Α
Repetitive avalanche energy (Note 3)		E _{AR}	4.5	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature range		T _{stg}	-55 to 150	°C



Weight: 1.7 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.78	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

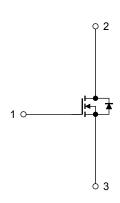
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 3.67 mH, R_G = 25 Ω , I_{AR} = 13 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.

Internal Connection



Electrical Characteristics (Ta = 25°C)

Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±1	μА
Drain cut-off current		I _{DSS}	V _{DS} = 450 V, V _{GS} = 0 V		_	10	μА
Drain-source bre	akdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	450	_	_	V
Gate threshold vo	oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source ON	-resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 6.5 A		0.38	0.46	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 6.5 A	1.5	6.0	_	S
Input capacitance		C _{iss}			1350	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz		6	_	
Output capacitance		C _{oss}			135	_	
Switching time	Rise time	t _r	$\begin{array}{c c} 10 \text{ V} \\ V_{GS} \\ 0 \text{ V} \\ \hline \\ 50 \Omega \end{array} \begin{array}{c} I_{D} = 6.5 \text{ A} & V_{OUT} \\ \hline \\ 8 \text{ R}_{L} = 30 \Omega \\ \hline \\ V_{DD} \approx 200 \text{ V} \\ \hline \\ Duty \leq 1\%, \ t_{W} = 10 \mu s \end{array}$	_	22		. ns
	Turn-on time	t _{on}			55	_	
	Fall time	t _f			15		
	Turn-off time	t _{off}		_	100	_	
Total gate charge		Qg		_	25	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 360 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 13 \text{ A}$	_	16	_	nC
Gate-drain charge		Q _{gd}		_	9	_	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	13	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	52	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 13 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 13 A, V _{GS} = 0 V,	_	1300	_	ns
Reverse recovery charge	Q _{rr}	dl _{DR} /dt = 100 A/μs	_	12	_	μС

Marking

